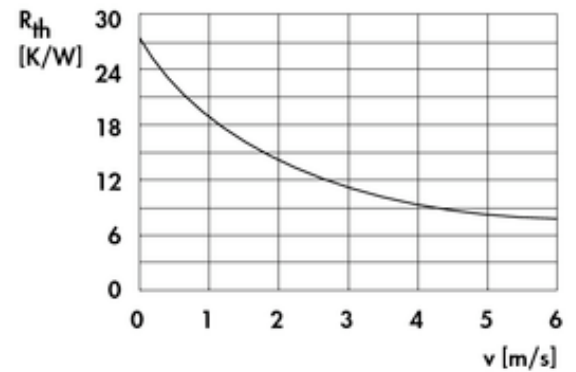
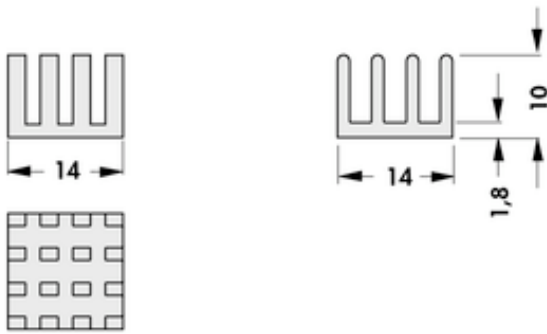
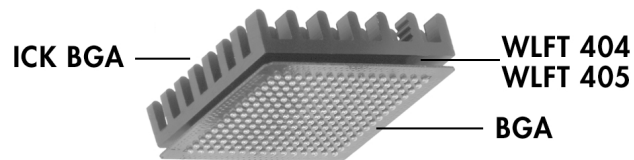


## Heatsinks for BGAs / **ICK BGA 14 x 14 x 10**



14 x 14 x 10 mm, for IC design BGA and others

### Parameters of article **ICK BGA 14 x 14 x 10**

|                                    |                                                                                        |
|------------------------------------|----------------------------------------------------------------------------------------|
| <b>R<sub>th</sub> [K/W]</b>        |  27.4 |
| <b>dissipation loss [W]</b>        |  2.3 |
| <b>mounting method</b>             | therm. conductive foil / therm. cond. adhesive                                         |
| <b>socket</b>                      | universal                                                                              |
| <b>suitable for processor type</b> | universal                                                                              |
| <b>width [mm]</b>                  | 14                                                                                     |
| <b>height [mm]</b>                 | 10                                                                                     |
| <b>plate thickness [mm]</b>        | 1.8                                                                                    |
| <b>length on stock [mm]</b>        | 14                                                                                     |
| <b>surface treatment</b>           | black anodised                                                                         |

### Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 14 x 14**

Thermally conductive foil both sides adhesive / **WLFT 405 14 x 14**